

## Combined Declaration and Power of Attorney for Patent Application

Docket Number: \_\_\_\_\_

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter that is claimed and for which a patent is sought on the invention entitled A RECEIVER AND A SIGNAL PROCESSING CIRCUIT THEREFOR, the specification of which is attached hereto unless the following box is checked:

was filed on \_\_\_\_\_;  
as United States Application Number or PCT International Application Number \_\_\_\_\_; and  
was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information that is material to patentability as defined in 37 C.F.R. § 1.56.

I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT international application, which designated at least one country other than the United States listed below, and have also identified below any foreign application for patent or inventor's certificate, or PCT international application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)	Priority	Claimed
200205347-8      SINGAPORE      02 September 2002	<input checked="" type="checkbox"/> Yes	<input type="checkbox"/> No
(Application No.)	(Country)	(Day/Month/Year Filed)

(Application No.)      (Country)      (Day/Month/Year Filed)

I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below.

(Application No.)      (Filing Date)

(Application No.)      (Filing Date)

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or under § 365(c) of any PCT international application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose information that is material to patentability as defined in 37 C.F.R. § 1.56 that became available between the filing date of the prior application and the national or PCT international filing date of this application.

Appl. No.  
Docket No. —

---

(Application No.)	(Filing Date)	(Status - patented, pending, abandoned)
-------------------	---------------	---

---

(Application No.)	(Filing Date)	(Status - patented, pending, abandoned)
-------------------	---------------	---

---

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

Jason C. Abair, Reg. No. 44,007

Ethan B. Andelman, Reg. No. 48,997

Michael J. Bell, Reg. No. 39,604

Andrew S. Brenc, Reg. No. 45,534

Sean D. Burdick, Reg. No. 51,513

Celine T. Callahan, Reg. No. 34,301

Jenny W. Chen, Reg. No. 44,604

Robin C. Chiang, Reg. No. 46,619

Chris Comuntzis, Reg. No. 31,097

James F. Davis, Reg. No. 21,072

Mark K. Dickson, Reg. No. 32,889

Thomas M. Dunham, Reg. No. 39,965

Heather H. Fan, Reg. No. P-51,664

Panpan Gao, Reg. No. 43,626

Darren J. Gold, Reg. No. 47,599

Alan M. Grimaldi, Reg. No. 26,599

J. Jay Giuliano, Reg. No. 41,810

Albert P. Halluin, Reg. No. 25,227

Leslie L. Jacobs, Jr., Reg. No. 40,659

Derek J. Jardieu, Reg. No. 44,483

Christopher L. Kelley, Reg. No. 42,714

Brian S.Y. Kim, Reg. No. 41,114

Viola T. Kung, Reg. No. 41,131

Robert C. Laurenson, Reg. No. 34,206

Joseph P. Lavelle, Reg. No. 31,036

Don F. Livornese, Reg. No. 32,040

Duane H. Mathiowetz, Reg. No. 33,420

Christopher A. Mathews, Reg. No. 35,944

Matthew J. Moore, Reg. No. 42,012

Andrew Y. Piatnicia, Reg. No. 40,772

Matthew Rainey, Reg. No. 32,291

William C. Rooklidge, Reg. No. 31,791

Glenn W. Rhodes, Reg. No. 31,790

Michael J. Stimson, Reg. No. 45,429

William F. Stryker, Reg. No. 52,258

William K. West, Reg. No. 22,057

Lorelei P. Westin, Reg. No. 52,353

Adam K. Whiting, Reg. No. 44,400

Jayna R. Whitt, Reg. No. 47,175

Karen K. Wong, Reg. No. 44,409

Wallace Wu, Reg. No. 45,380

Matthew S. Zises, Reg. No. 47,246

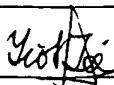
Send Correspondence to:

**Matthew Rainey**  
**HOWREY SIMON ARNOLD & WHITE, LLP**  
301 Ravenswood Avenue  
Box No. 34  
Menlo Park, CA 94025  
Facsimile: (415) 848-4999

Direct Telephone Calls to: (415) 848-4950

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Appl. No.  
Docket No.

Full name of sole or first inventor	Theng Tee <u>YEO</u>	
Inventor's signature		
Date	15 - AUG - 2003	
Residence	Blk 483 Jurong West St 41 #07-244, Singapore 640483	
Citizenship	Malaysia	
Mailing Address	Blk 483 Jurong West St 41 #07-244, Singapore 640483	
Full name of second inventor	Hwa Seng <u>YAP</u>	
Second inventor's signature		
Date	19 - AUG - 2003	
Residence	Blk 272 Toh Guan Road #09-77, Singapore 600272	
Citizenship	Singapore	
Mailing Address	Blk 272 Toh Guan Road #09-77, Singapore 600272	
Full name of third inventor	Masaaki <u>ITOH</u>	
Third inventor's signature		
Date	19 - AUG - 2003	
Residence	20 Science Park Road #02-06/10 Teletech Park, Singapore Science Park 2, Singapore 117674	
Citizenship	Japan	
Mailing Address	20 Science Park Road #02-06/10 Teletech Park, Singapore Science Park 2, Singapore 117674	